



- NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 B) ALL DIMENSIONS ARE IN MILLIMETERS
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D) () IS REFERENCE
 E) [] IS ASS'Y QUALITY
 F) DRAWING FILENAME: MOD23DCREV2.0
 G) FAIRCHILD SEMICONDUCTOR

LAND PATTERN RECOMMENDATIONS